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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 35010.5-2018

**Semiconductor die products -- Part 5: Requirements for
concerning electrical simulation**

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Foreword

GB/T 35010 "Semiconductor Chip Products" is divided into the following parts.

- Part 1. Procurement and use requirements;
- Part 2. Data exchange format;
- Part 3. Guidelines for handling, packaging and storage;
- Part 4. Chip user and supplier requirements;
- Part 5. Electrical Simulation Requirements;
- Part 6. Thermal Simulation Requirements;
- Part 7. XML format for data exchange;
- Part 8. EXPRESS format for data exchange.

This part is Part 5 of GB/T 35010.

This section was drafted in accordance with the rules given in GB/T 1.1-2009.

This section uses the translation method equivalent to using IEC 62258-5:2006 "semiconductor chip products Part 5. electrical simulation information requirements."

The Chinese documents that have a consistent correspondence with the normatively quoted international documents in this section are as follows.

- GB/T 35010.1-2018 Semiconductor chip products Part 1. Procurement and use requirements (IEC 62258-1:2009,

IDT)

- GB/T 35010.2-2018 Semiconductor chip products Part 2. Data exchange format (IEC 62258-2:2011, IDT)

This section made the following editorial changes.

--- Taking into account the adaptation of our standards system, the name will be changed to "Semiconductor chip products - Part 5. Electrical simulation requirements".

1 Scope

This part of GB/T 35010 is used to guide the production, supply and use of semiconductor chip products. Semiconductor chip products include.

- * Wafers;
- * Single bare chip;
- * Chips and wafers with interconnect structures;
- * Smallest or partially packaged chips and wafers.

This section provides the required electrical simulation information to promote the electronic data, electronic systems electrical behavior and functional verification simulation model

usage of. The electronic system includes a semiconductor bare chip with or without an interconnect structure, and/or a minimally packaged semiconductor chip. This section is

In order to make all aspects of the chip product supply chain meet the requirements of IEC 62258-1 and IEC 62258-2.

2 Normative references

The following documents are indispensable for the application of this document. For dated references, only dated versions apply to this article

Pieces. For undated references, the latest version (including all amendments) applies to this document.

IEC 62258-1 Semiconductor chip products Part 1. Procurement and use (Semiconductor die products-Part 1.

Procurementanduse)

IEC 62258-2 Semiconductor chip products Part 2. Data interchange formats (Semiconductor die products-Part 2.

Exchangedataformats)

3 Terms and definitions

The terms and definitions defined in IEC 62258-1 apply to this document.

4 General

According to the provisions of IEC 62258-1, the supplier of chip products should provide a complete data package, which should contain the user's design,

Necessary and sufficient information needed at all stages of procurement, manufacturing, and testing.

At the same time, most of the information provided should meet the relevant standards and be disclosed in the public domain, and the information source can be in the form of manufacturer data tables.

The traceability of the form does not require the manufacturer to assume the obligation of information disclosure. Any information involving patent or business sensitive information, manufacturers can adopt

Take a non-disclosed form for protection.

The requirements and recommendations provided in this section apply to the electrical model that performs the following simulations.

- * Analysis of signal propagation within the electronic system;
- * Verification of the functionality of the electronic system;
- * verification of timing requirements;
- * Verify testability.

See Appendix A for additional information on the electrical simulation model.